

CONDUCTIVE ADHESIVE FILM

Abstract

An adhesive film that shows excellent heat resistance while showing excellent stress relaxation property, which further shows high conductivity that enables application to rear-side electrodes for power semiconductors without the use of expensive precious metals such as silver, which also shows sufficient adhesive strength without protruding from the device, and a method for processing semiconductors using the same, are provided.

In particular, a conductive adhesive film, which comprises two or more types of metal particles including at least Cu and a polymer that has a polydimethylsiloxane structure, is provided. Further, a dicing die bonding film, which is obtained by laminating a dicing tape on said conductive adhesive film, as well as a method for processing semiconductor wafers using said adhesive film and said dicing die bonding film, are provided.

[Figure 1]